

### 3.3-V CAN TRANSCEIVERS

#### **FEATURES**

- Bus-Pin Fault Protection Exceeds ±36 V
- Bus-Pin ESD Protection Exceeds 16-kV HBM
- GIFT/ICT Compliant (SN65HVD234)
- Compatible With ISO 11898
- Signaling Rates<sup>(1)</sup> up to 1 Mbps
- Extended -7-V to 12-V Common-Mode Range
- High-Input Impedance Allows for 120 Nodes
- LVTTL I/Os Are 5-V Tolerant
- Adjustable Driver Transition Times for Improved Signal Quality
- Unpowered Node Does Not Disturb the Bus
- Low-Current Standby Mode . . . 200-μA Typical
- Low-Current Sleep Mode . . . 50-nA Typical (SN65HVD234)
- Thermal Shutdown Protection
- Power-Up/Down Glitch-Free Bus Inputs and Outputs
  - High Input Impedance With Low V<sub>CC</sub>
  - Monolithic Output During Power Cycling
- Loopback for Diagnostic Functions Available (SN65HVD233)
- Loopback for Autobaud Function Available (SN65HVD235)
- DeviceNet Vendor ID #806
- (1) The signaling rate of a line is the number of voltage transitions that are made per second expressed in the units bps (bits per second).

### **APPLICATIONS**

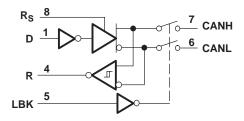
- CAN Data Bus
- Industrial Automation
  - DeviceNet<sup>™</sup> Data Buses
  - Smart Distributed Systems (SDS™)
- SAE J1939 Standard Data Bus Interface
- NMEA 2000 Standard Data Bus Interface
- ISO 11783 Standard Data Bus Interface

#### DESCRIPTION

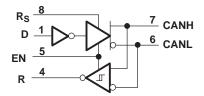
The SN65HVD233, SN65HVD234, and SN65HVD235 are used in applications employing the controller area network (CAN) serial communication physical layer in accordance with the ISO 11898 standard. As a CAN transceiver, each provides transmit and receive capability between the differential CAN bus and a CAN controller, with signaling rates up to 1 Mbps.

Designed for operation in especially harsh environments, the devices feature cross-wire, overvoltage and loss of ground protection to  $\pm 36$  V, with overtemperature protection and common-mode transient protection of  $\pm 100$  V. These devices operate over a -7-V to 12-V common-mode range with a maximum of 60 nodes on a bus.

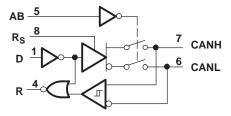
## SN65HVD233 FUNCTIONAL BLOCK DIAGRAM



## SN65HVD234 FUNCTIONAL BLOCK DIAGRAM



#### SN65HVD235 FUNCTIONAL BLOCK DIAGRAM



M

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

DeviceNet is a trademark of Open DeviceNet Vendor Association.





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### **DESCRIPTION (CONTINUED)**

If the common-mode range is restricted to the ISO-11898 Standard range of -2 V to 7 V, up to 120 nodes may be connected on a bus. These transceivers interface the single-ended CAN controller with the differential CAN bus found in industrial, building automation, and automotive applications.

The R<sub>S</sub>, pin 8 of the SN65HVD233, SN65HVD234, and SN65HVD235 provides for three modes of operation: high-speed, slope control, or low-power standby mode. The high-speed mode of operation is selected by connecting pin 8 directly to ground, allowing the driver output transistors to switch on and off as fast as possible with no limitation on the rise and fall slope. The rise and fall slope can be adjusted by connecting a resistor to ground at pin 8, since the slope is proportional to the pin's output current. Slope control is implemented with a resistor value of 10 k $\Omega$  to achieve a slew rate of 915 V/ $\mu$ s and a value of 100 k $\Omega$  to achieve 9 2.0 V/ $\mu$ s slew rate. For more information about slope control, refer to the application information section.

The SN65HVD233, SN65HVD234, and SN65HVD235 enter a low-current standby mode during which the driver is switched off and the receiver remains active if a high logic level is applied to pin 8. The local protocol controller reverses this low-current standby mode when it needs to transmit to the bus.

A logic high on the loopback LBK pin 5 of the SN65HVD233 places the bus output and bus input in a high-impedance state. The remaining circuit remains active and available for driver to receiver loopback, self-diagnostic node functions without disturbing the bus.

The SN65HVD234 enters an ultralow-current sleep mode in which both the driver and receiver circuits are deactivated if a low logic level is applied to EN pin 5. The device remains in this sleep mode until the circuit is reactivated by applying a high logic level to pin 5.

The AB pin 5 of the SN65HVD235 implements a bus listen-only loopback feature which allows the local node controller to synchronize its baud rate with that of the CAN bus. In autobaud mode, the driver's bus output is placed in a high-impedance state while the receiver's bus input remains active. For more information on the autobaud mode, refer to the application information section.

#### AVAILABLE OPTIONS(1)

PART NUMBER	LOW POWER MODE S CO		DIAGNOSTIC LOOPBACK	AUTOBAUD LOOPBACK
SN65HVD233D	200-μA standby mode	Adjustable	Yes	No
SN65HVD234D	200-μA standby mode or 50-nA sleep mode	Adjustable	No	No
SN65HVD235D	200-μA standby mode	Adjustable	No	Yes

For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI
web site at www.ti.com.

#### **ORDERING INFORMATION**

PACKAGE (D)	Marked as
SN65HVD233D	VD222
SN65HVD233DR <sup>(1)</sup>	VP233
SN65HVD234D	VP234
SN65HVD234DR <sup>(1)</sup>	VP234
SN65HVD235D	VP235
SN65HVD235DR <sup>(1)</sup>	VP235

(1) R suffix indicates tape and reel.



#### **POWER DISSIPATION RATINGS**

PACKAGE	CIRCUIT BOARD	T <sub>A</sub> ≤ 25°C POWER RATING	DERATING FACTOR <sup>(1)</sup> ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 85°C POWER RATING	T <sub>A</sub> = 125°C POWER RATING
D	Low-K	596.6 mW	5.7 mW/°C	255.7 mW	28.4 mW
D	High-K	1076.9 mW	10.3 mW/°C	461.5 mW	51.3 mW

<sup>(1)</sup> This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

### ABSOLUTE MAXIMUM RATINGS(1) (2)

over operating free-air temperature range unless otherwise noted

				Value	UNIT
V <sub>CC</sub>	Supply voltage range		-0.3 to 7	V	
	Voltage range at any bu	is terminal (CANH or CANL)		-36 to 36	V
	Voltage input range, tra	nsient pulse, CANH and CANL	-100 to 100	V	
VI	Input voltage range, (D,	R, R <sub>S</sub> , EN, LBK, AB)		-0.5 to 7	V
Io	Receiver output current	-10 to 10	mA		
	Electrostatic discharge	Human Body Model (3)	CANH, CANL and GND	16	kV
		Human Body Model (3)	All pins	3	kV
	Electrostatic discharge	Charged-Device Mode (4)	All pins	1	kV
	Continuous total power	Continuous total power dissipation			
$T_{J}$	Operating junction temp	erature		150	°C

<sup>(1)</sup> Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### RECOMMENDED OPERATING CONDITIONS

			MIN	TYP MAX	UNIT
$V_{CC}$	Supply voltage		3	3.6	
	Voltage at any bus terminal (separat	ely or common mode)	-7	12	
$V_{IH}$	High-level input voltage	D, EN, AB, LBK	2	5.5	V
$V_{IL}$	Low-level input voltage	D, EN, AB, LBK	0	0.8	
$V_{ID}$	Differential input voltage		-6	6	
	Resistance from R <sub>S</sub> to ground		0	100	kΩ
$V_{I(Rs)}$	Input Voltage at R <sub>S</sub> for standby		0.75 V <sub>CC</sub>	5.5	V
	Llich level cutout current	Driver	-50	7 12 2 5.5 0 0.8 6 6 6 0 100 5.5 0 50 10 150	A
I <sub>OH</sub>	High-level output current	Receiver	-10		mA
	Low lovel output ourrent	Driver		5.5 5.5 5.5 50 10	A
I <sub>OL</sub>	Low-level output current	Receiver		10	mA
$T_{J}$	Operating junction temperature	HVD233, HVD234, HVD235		150	°C
$T_A$	Operating free-air temperature <sup>(1)</sup>	HVD233, HVD234, HVD235	-40	125	°C

<sup>(1)</sup> Maximum free-air temperature operation is allowed as long as the device maximum junction temperature is not exceeded.

<sup>(2)</sup> All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.

<sup>(3)</sup> Tested in accordance with JEDEC Standard 22, Test Method A114-A.

<sup>(4)</sup> Tested in accordance with JEDEC Standard 22, Test Method C101.



### **DRIVER ELECTRICAL CHARACTERISTICS**

	PARAME	ETER		TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
.,	Bus output voltage		CANH	Data V Data V Cas Figure 4 and Figure 2	2.45		$V_{CC}$	V
$V_{O(D)}$	(Dominant)		CANL	D at 0 V, R <sub>S</sub> at 0 V, See Figure 1 and Figure 2	0.5		1.25	V
.,	Bus output voltage		CANH	Data V Data V Cas Firms 4 and Firms 6		2.3		
Vo	(Recessive)		CANL	D at 3 V, R <sub>S</sub> at 0 V, See Figure 1 and Figure 2		2.3		V
	D''' C'-l	-11 (D -		D at 0 V, R <sub>S</sub> at 0 V, See Figure 1 and Figure 2	1.5	2	3	
$V_{OD(D)}$	Differential output voltage (Dominant)		minant)	D at 0 V, R <sub>S</sub> at 0 V, See Figure 2 and Figure 3	1.2	2	3	V
.,	D''' '' ' ' ' ' '	ı. (D		D at 3 V, R <sub>S</sub> at 0 V, See Figure 1 and Figure 2	-120		12	mV
$V_{OD}$	Differential output voltage (Recessive)  Peak-to-peak common-mode output voltage		cessive)	D at 3 V, R <sub>S</sub> at 0 V, No Load	-0.5		0.05	V
V <sub>OC(pp)</sub>	Peak-to-peak comm	on-mode	output voltage	See Figure 10		1		V
I <sub>IH</sub>	High-level input curr	ent	D, EN, LBK, AB	D at 2 V	-30		30	μΑ
I <sub>IL</sub>	Low-level input curre	ent	D, EN, LBK, AB	D at 0.8 V	-30		30	μΑ
			II.	V <sub>CANH</sub> = -7 V, CANL Open, See Figure 15	-250			
	0			V <sub>CANH</sub> = 12 V, CANL Open, See Figure 15			1	
los	Short-circuit output	current		V <sub>CANL</sub> = -7 V, CANH Open, See Figure 15	-1			mA
				V <sub>CANL</sub> = 12 V, CANH Open, See Figure 15			250	
Co	Output capacitance			See receiver input capacitance				
I <sub>IRs(s)</sub>	R <sub>S</sub> input current for	standby		R <sub>S</sub> at 0.75 V <sub>CC</sub>	-10			μΑ
- (-)		Sleep		EN at 0 V, D at V <sub>CC</sub> , R <sub>S</sub> at 0 V or V <sub>CC</sub>		0.05	2	
		Standby		$R_{S}$ at $V_{CC},D$ at $V_{CC},AB$ at 0 V, LBK at 0 V, EN at $V_{CC}$		200	600	μΑ
I <sub>CC</sub>	Supply current	Dominan	t	D at 0 V, No Load, AB at 0 V, LBK at 0 V, R <sub>S</sub> at 0 V, EN at V <sub>CC</sub>			6	m Λ
	Rece		/e	D at V <sub>CC</sub> , No Load, AB at 0 V,LBK at 0 V, R <sub>S</sub> at 0 V, EN at V <sub>CC</sub>			6	mA

<sup>(1)</sup> All typical values are at  $25^{\circ}$ C and with a 3.3 V supply.



### **DRIVER SWITCHING CHARACTERISTICS**

	PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT	
		R <sub>S</sub> at 0 V, See Figure 4		35	85		
$t_{PLH}$	Propagation delay time, low-to-high-level output	$R_S$ with 10 k $\Omega$ to ground, See Figure 4		70	125	ns	
	low to high level output	$R_S$ with 100 k $\Omega$ to ground, See Figure 4		500	870		
		R <sub>S</sub> at 0 V, See Figure 4		70	120		
$t_{PHL}$	Propagation delay time,  HL high-to-low-level output	$R_S$ with 10 k $\Omega$ to ground, See Figure 4		130	180	ns	
	riight to low level output	$R_S$ with 100 k $\Omega$ to ground, SeeFigure 4		870	1200		
		R <sub>S</sub> at 0 V, See Figure 4		35			
t <sub>sk(p)</sub>	<sub>sk(p)</sub> Pulse skew ( t <sub>PHL</sub> - t <sub>PLH</sub>  )	$R_S$ with 10 k $\Omega$ to ground, See Figure 4		60		ns	
		$R_S$ with 100 k $\Omega$ to ground, SeeFigure 4		370			
t <sub>r</sub>	Differential output signal rise time	D. at 0.1/ Can Figure 4	20		70		
t <sub>f</sub>	Differential output signal fall time	R <sub>S</sub> at 0 V, See Figure 4	20		70	ns	
t <sub>r</sub>	Differential output signal rise time	D with 40   O to word   O to Figure 4	30		135		
t <sub>f</sub>	Differential output signal fall time	R <sub>S</sub> with 10 kΩ to ground, See Figure 4	30		135	ns	
t <sub>r</sub>	Differential output signal rise time	D with 400 l O to several l O to Finance 4	350		1400		
t <sub>f</sub>	Differential output signal fall time	$R_S$ with 100 kΩ to ground, See Figure 4	350		1400	ns	
t <sub>en(s)</sub>	Enable time from standby to dominant	0 5		0.6	1.5		
t <sub>en(z)</sub>	Enable time from sleep to dominant	See Figure 8 and Figure 9		1	5	μs	

<sup>(1)</sup> All typical values are at 25°C and with a 3.3 V supply.



### RECEIVER ELECTRICAL CHARACTERISTICS

	PARAMI	ETER	TEST CO	ONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
$V_{IT+}$	Positive-going inp	out threshold voltage				750	900	
V <sub>IT</sub>	Negative-going in	put threshold voltage	AB at 0 V, LBK at 0 V, EN at V <sub>CC</sub> , See Table 1		500	650		mV
V <sub>hys</sub>	Hysteresis voltag	e (V <sub>IT+</sub> – V <sub>IT</sub> )				100		
V <sub>OH</sub>	High-level output	voltage	$I_O = -4$ mA, See Figure 6		2.4			V
V <sub>OL</sub>	Low-level output	voltage	I <sub>O</sub> = 4 mA, See Figure 6				0.4	V
			CANH or CANL at 12 V		150		500	
	Due input summet		CANH or CANL at 12 V, V <sub>CC</sub> at 0 V	Other bus pin at 0 V, D at 3 V, AB at 0 V,	200		600	4
lı .	Bus input current		CANH or CANL at -7 V		-610		-150	μΑ
			CANH or CANL at –7 V, V <sub>CC</sub> at 0 V		-450		-130	
C <sub>I</sub>	Input capacitance	(CANH or CANL)		Pin-to-ground, $V_I = 0.4 \sin (4E6\pi t) + 0.5V$ , D at 3 V, AB at 0 V, LBK at 0 V, EN at $V_{CC}$		40		, E
C <sub>ID</sub>	Differential input	capacitance	Pin-to-pin, $V_I = 0.4 \sin (4E)$ AB at 0 V, LBK at 0 V, EN			20		pF
R <sub>ID</sub>	Differential input	resistance	D at 2 V AB at 0 V I BK a	+ 0 \/ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	40		100	kΩ
R <sub>IN</sub>	Input resistance (	CANH or CANL)	D at 3 V, AB at 0 V, LBK a	II U V, EIN AL VCC	20		50	K\$2
		Sleep	EN at 0 V, D at V <sub>CC</sub> , R <sub>S</sub> at	0 V or V <sub>CC</sub>		0.05	2	μA
		Standby	$R_S$ at $V_{CC}$ , D at $V_{CC}$ , AB at	t 0 V, LBK at 0 V, EN at V <sub>CC</sub>		200	600	μΑ
I <sub>CC</sub>	Supply current	Dominant	D at 0 V, No Load, $R_S$ at 0 EN at $V_{CC}$	V, LBK at 0 V, AB at 0 V,			6	mA
		Recessive	D at $V_{CC}$ , No Load, $R_S$ at 0 EN at $V_{CC}$	OV, LBK at 0 V, AB at 0 V,			6	ША

<sup>(1)</sup> All typical values are at 25°C and with a 3.3 V supply.



### RECEIVER SWITCHING CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN TYP <sup>(1)</sup>	MAX	UNIT
t <sub>PLH</sub>	Propagation delay time, low-to-high-level output		35	60	
t <sub>PHL</sub>	Propagation delay time, high-to-low-level output		35	60	
t <sub>sk(p)</sub>	Pulse skew ( t <sub>PHL</sub> - t <sub>PLH</sub>  )	See Figure 6	7		ns
t <sub>r</sub>	Output signal rise time		2	5	
t <sub>f</sub>	Output signal fall time		2	5	

<sup>(1)</sup> All typical values are at  $25^{\circ}$ C and with a 3.3 V supply.

### **DEVICE SWITCHING CHARACTERISTICS**

	PARAMETER		TEST CONDITIONS	MIN TYP <sup>(1)</sup>	MAX	UNIT
t <sub>(LBK)</sub>	Loopback delay, driver input to receiver output	HVD233	See Figure 12	7.5	12	ns
t <sub>(AB1)</sub>	Loopback delay, driver input to receiver output	LIV/Door	See Figure 13	10	20	ns
t <sub>(AB2)</sub>	Loopback delay, bus input to receiver output	HVD235	See Figure 14	35	60	ns
			R <sub>S</sub> at 0 V, See Figure 11	70	135	
t <sub>(loop1)</sub>	Total loop delay, driver input to receiver output, recessive to dominant	$R_S$ with 10 k $\Omega$ to ground, See Figure 11	105	190	ns	
	recessive to dominant		$R_S$ with 100 k $\Omega$ to ground, See Figure 11	535	20 60 135	
			R <sub>S</sub> at 0 V, See Figure 11	70	135	
t <sub>(loop2)</sub>	Total loop delay, driver input to receiver output, dominant to recessive		$R_S$ with 10 k $\Omega$ to ground, See Figure 11	105	190	ns
			$R_S$ with 100 k $\Omega$ to ground, See Figure 11	535	1000	

<sup>(1)</sup> All typical values are at 25°C and with a 3.3 V supply.



### PARAMETER MEASUREMENT INFORMATION

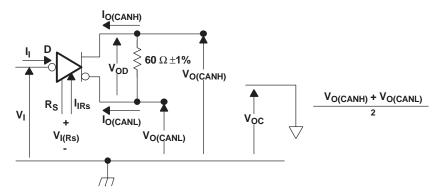


Figure 1. Driver Voltage, Current, and Test Definition

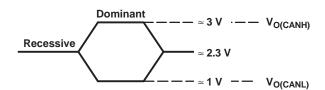


Figure 2. Bus Logic State Voltage Definitions

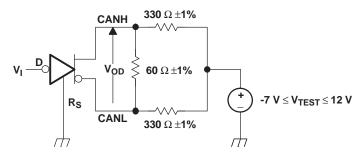
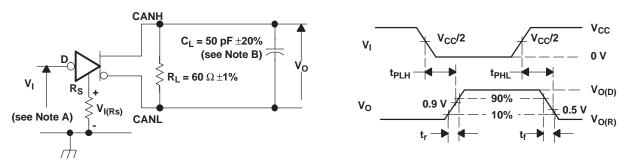


Figure 3. Driver V<sub>OD</sub>



- A. The input pulse is supplied by a generator having the following characteristics: Pulse repetition rate (PRR)  $\leq$  125 kHz, 50% duty cycle,  $t_r \leq$  6 ns,  $t_f \leq$  6 ns,  $Z_O =$  50  $\Omega$ .
- B. C<sub>L</sub> includes fixture and instrumentation capacitance.

Figure 4. Driver Test Circuit and Voltage Waveforms



### PARAMETER MEASUREMENT INFORMATION (continued)

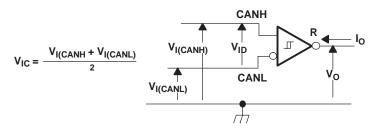
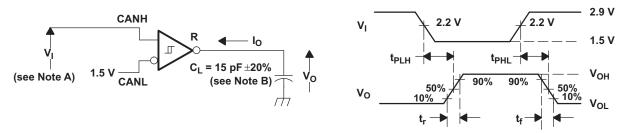


Figure 5. Receiver Voltage and Current Definitions

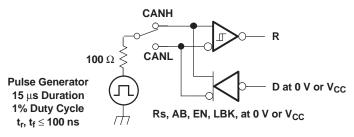


- A. The input pulse is supplied by a generator having the following characteristics: Pulse repetition rate (PRR)  $\leq$  125 kHz, 50% duty cycle,  $t_r \leq$  6 ns,  $t_f \leq$  6 ns,  $Z_O =$  50  $\Omega$ .
- B. C<sub>L</sub> includes fixture and instrumentation capacitance.

Figure 6. Receiver Test Circuit and Voltage Waveforms

**INPUT** OUTPUT **MEASURED** V<sub>CANH</sub> R VCANL  $|V_{ID}|$ -6.1 V -7 V L 900 mV 12 V 11.1 V L 900 mV  $V_{OL}$ -1 V -7 V L 6 V 12 V 6 V L 6 V -6.5 V -7 V Н 500 mV 12 V 11.5 V Н 500 mV -7 V -1 V Н 6 V  $V_{OH}$ 6 V 12 V Н 6 V Open Open Н Χ

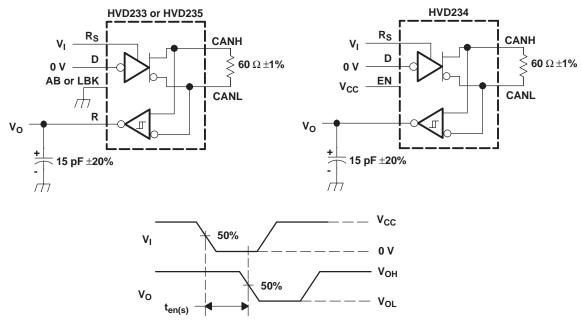
**Table 1. Differential Input Voltage Threshold Test** 



NOTE: This test is conducted to test survivability only. Data stability at the R output is not specified.

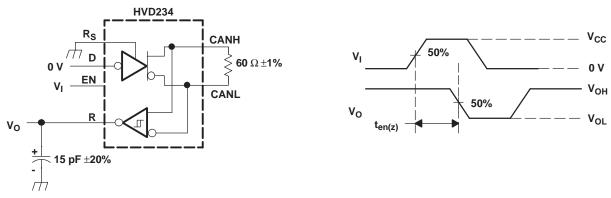
Figure 7. Test Circuit, Transient Over Voltage Test





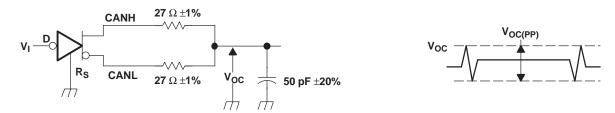
NOTE: All V<sub>I</sub> input pulses are supplied by a generator having the following characteristics:  $t_r$  or  $t_f \le 6$  ns, pulse repetition rate (PRR) = 125 kHz, 50% duty cycle.

Figure 8. t<sub>en(s)</sub> Test Circuit and Voltage Waveforms



NOTE: All V<sub>I</sub> input pulses are supplied by a generator having the following characteristics:  $t_r$  or  $t_f \le 6$  ns, pulse repetition rate (PRR) = 50 kHz, 50% duty cycle.

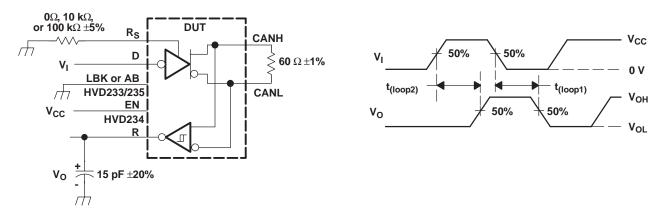
Figure 9. t<sub>en(z)</sub> Test Circuit and Voltage Waveforms



NOTE: All V<sub>I</sub> input pulses are supplied by a generator having the following characteristics:  $t_r$  or  $t_f \le 6$  ns, pulse repetition rate (PRR) = 125 kHz, 50% duty cycle.

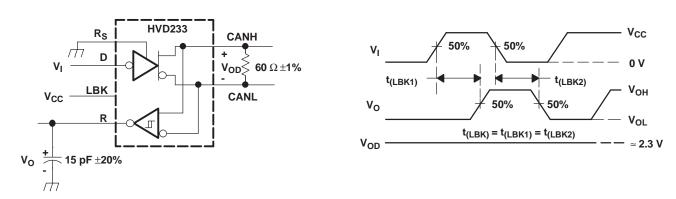
Figure 10. V<sub>OC(pp)</sub> Test Circuit and Voltage Waveforms





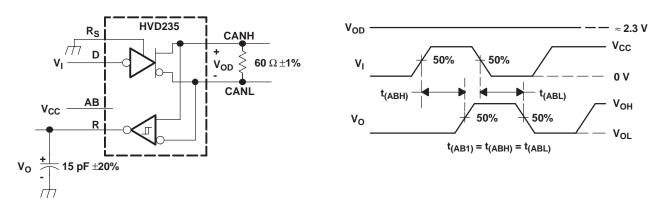
NOTE: All V<sub>I</sub> input pulses are supplied by a generator having the following characteristics:  $t_r$  or  $t_f \le 6$  ns, pulse repetition rate (PRR) = 125 kHz, 50% duty cycle.

Figure 11. t<sub>(loop)</sub> Test Circuit and Voltage Waveforms



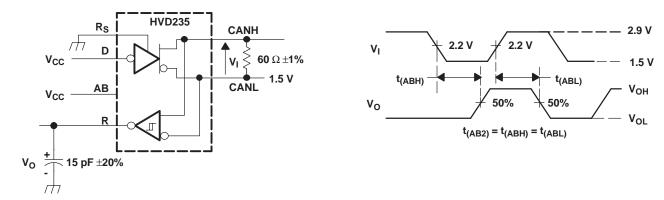
NOTE: All V<sub>I</sub> input pulses are supplied by a generator having the following characteristics:  $t_r$  or  $t_f \le 6$  ns, pulse repetition rate (PRR) = 125 kHz, 50% duty cycle.

Figure 12. t<sub>(LBK)</sub> Test Circuit and Voltage Waveforms



NOTE: All V<sub>I</sub> input pulses are supplied by a generator having the following characteristics:  $t_r$  or  $t_f \le 6$  ns, pulse repetition rate (PRR) = 125 kHz, 50% duty cycle.

Figure 13. t<sub>(AB1)</sub> Test Circuit and Voltage Waveforms



NOTE: All V<sub>I</sub> input pulses are supplied by a generator having the following characteristics:  $t_r$  or  $t_f \le 6$  ns, pulse repetition rate (PRR) = 125 kHz, 50% duty cycle.

Figure 14. t<sub>(AB2)</sub> Test Circuit and Voltage Waveforms

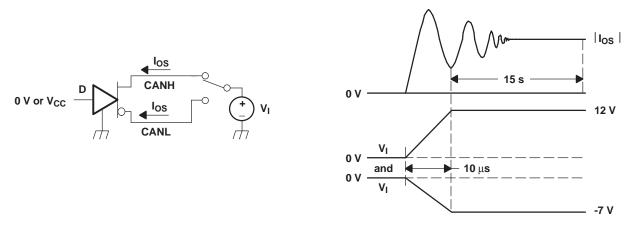
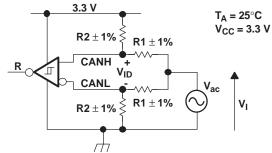


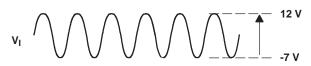
Figure 15. I<sub>OS</sub> Test Circuit and Waveforms





The R Output State Does Not Change During Application of the Input Waveform.

$V_{\text{ID}}$	R1	R2
500 mV	50 Ω	<b>280</b> Ω
900 mV	50 Ω	130 Ω

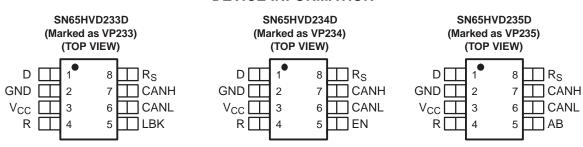


NOTE: All input pulses are supplied by a generator with  $f \le 1.5$  MHz.

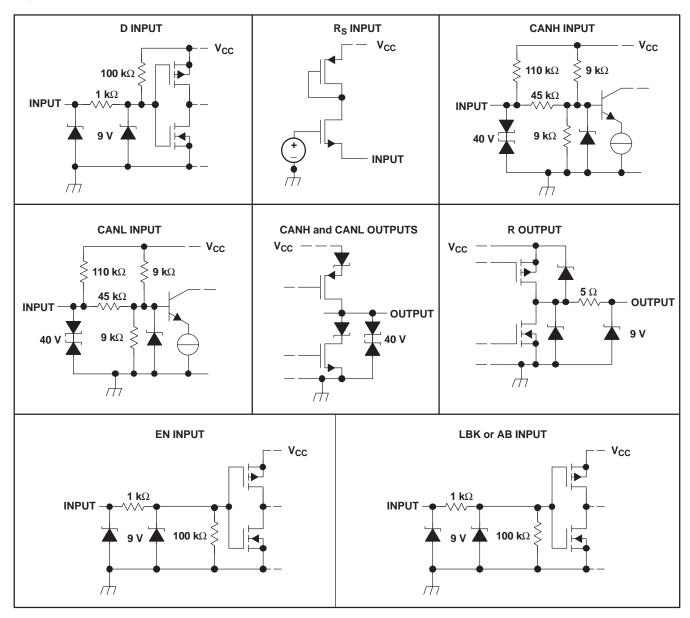
Figure 16. Common-Mode Voltage Rejection



### **DEVICE INFORMATION**



### **EQUIVALENT INPUT AND OUTPUT SCHEMATIC DIAGRAMS**





#### **Table 2. Thermal Characteristics**

	PARAMETERS	TEST CONDITIONS		UNIT
$\theta_{JA}$	Junction-to-ambient thermal resistance <sup>(1)</sup>	Low-K <sup>(2)</sup> board, no air flow		°C/W
	Junction-to-ambient thermal resistance	High-K <sup>(3)</sup> board, no air flow	101	- C/VV
$\theta_{JB}$	Junction-to-board thermal resistance	High-K <sup>(3)</sup> board, no air flow	82.8	°C/W
$\theta_{JC}$	Junction-to-case thermal resistance		26.5	°C/W
P <sub>(AVG)</sub>	Average power dissipation	$R_L$ = 60 Ω, $R_S$ at 0 V, input to D a 1-MHz 50% duty cycle square wave $V_{CC}$ at 3.3 V, $T_A$ = 25°C	36.4	mW
T <sub>(SD)</sub>	Thermal shutdown junction temperature		170	°C

- (1) See TI literature number SZZA003 for an explanation of this parameter.
- (2) JESD51-3 low effective thermal conductivity test board for leaded surface mount packages.
- (3) JESD51-7 high effective thermal conductivity test board for leaded surface mount packages.

### **FUNCTION TABLES**

DRIVER (SN65HVD233 or SN65HVD235)							
	INPUTS			OUTPUTS			
D	LBK/AB	R <sub>s</sub>	CANH	CANL	BUS STATE		
Х	Х	> 0.75 V <sub>CC</sub>	Z	Z	Recessive		
L	L or open	< 0.22.1/	Н	L	Dominant		
H or open	Х	≤ 0.33 V <sub>CC</sub>	Z	Z	Recessive		
Х	Н	≤ 0.33 V <sub>CC</sub>	Z	Z	Recessive		

RECEIVER (SN65HVD233)								
	INPUTS							
BUS STATE	$V_{ID} = V_{(CANH)} - V_{(CANL)}$	LBK	D	R				
Dominant	V <sub>ID</sub> ≥ 0.9 V	L or open	Х	L				
Recessive	V <sub>ID</sub> ≤ 0.5 V or open	L or open	H or open	Н				
?	0.5 V < V <sub>ID</sub> <0.9 V	L or open	H or open	?				
Х	Х	11	L	L				
Х	X	- Н	Н	Н				

RECEIVER (SN65HVD235) <sup>(1)</sup>							
	INPUTS						
BUS STATE	$V_{ID} = V_{(CANH)} - V_{(CANL)}$	$V_{ID} = V_{(CANH)} - V_{(CANL)}$ AB D					
Dominant	V <sub>ID</sub> ≥ 0.9 V	L or open	Х	L			
Recessive	V <sub>ID</sub> ≤ 0.5 V or open	L or open	H or open	Н			
?	$0.5 \text{ V} < \text{V}_{\text{ID}} < 0.9 \text{ V}$	L or open	H or open	?			
Dominant	V <sub>ID</sub> ≥ 0.9 V	Н	Х	L			
Recessive	V <sub>ID</sub> ≤ 0.5 V or open	Н	Н	Н			
Recessive	V <sub>ID</sub> ≤ 0.5 V or open	Н	L	L			
?	0.5 V < V <sub>ID</sub> <0.9 V	Н	L	L			

(1) H = high level; L = low level; Z = high impedance; X = irrelevant; ? = indeterminate



DRIVER (SN65HVD234)							
	INPUTS		OUTPUTS				
D	EN	R <sub>s</sub>	CANH	CANL	BUS STATE		
L	Н	≤ 0.33 V <sub>CC</sub>	Н	L	Dominant		
Н	Х	≤ 0.33 V <sub>CC</sub>	Z	Z	Recessive		
Open	Х	Х	Z	Z	Recessive		
Х	Х	> 0.75 V <sub>CC</sub>	Z	Z	Recessive		
Х	L or open	Х	Z	Z	Recessive		

RECEIVER (SN65HVD234) <sup>(1)</sup>						
	INPUTS					
BUS STATE	$V_{ID} = V_{(CANH)} - V_{(CANL)}$	EN	R			
Dominant	V <sub>ID</sub> ≥ 0.9 V	Н	L			
Recessive	V <sub>ID</sub> ≤ 0.5 V or open	Н	Н			
?	0.5 V < V <sub>ID</sub> <0.9 V	Н	?			
X	X	L or open	Н			

(1) H = high level; L = low level; Z = high impedance; X = irrelevant; ? = indeterminate



### TYPICAL CHARACTERISTICS

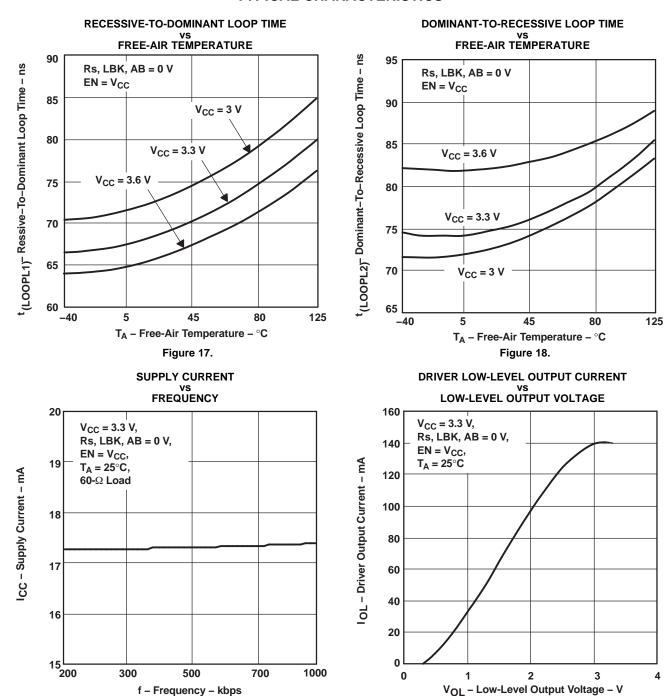
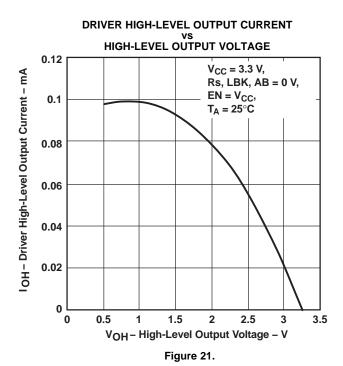


Figure 19.

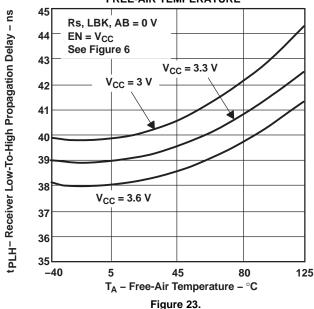
Figure 20.



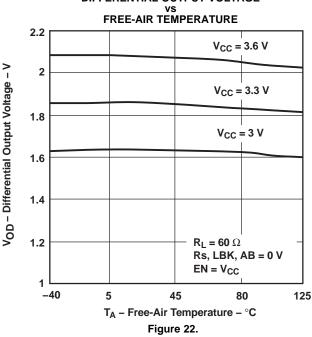
### TYPICAL CHARACTERISTICS (continued)



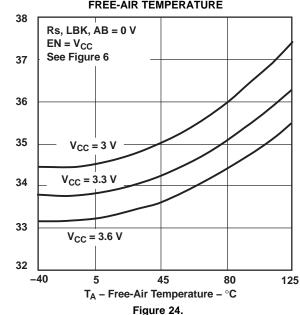
### **RECEIVER LOW-TO-HIGH PROPAGATION DELAY** vs FREE-AIR TEMPERATURE



# **DIFFERENTIAL OUTPUT VOLTAGE**



### **RECEIVER HIGH-TO-LOW PROPAGATION DELAY** vs FREE-AIR TEMPERATURE

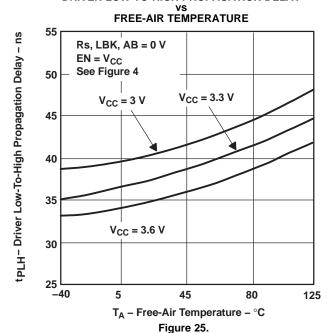


tpHL- Receiver High-To-Low Propagation Delay - ns



### **TYPICAL CHARACTERISTICS (continued)**

### **DRIVER LOW-TO-HIGH PROPAGATION DELAY**



### DRIVER HIGH-TO-LOW PROPAGATION DELAY

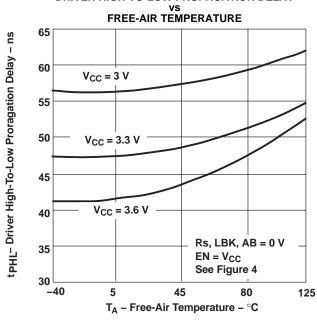
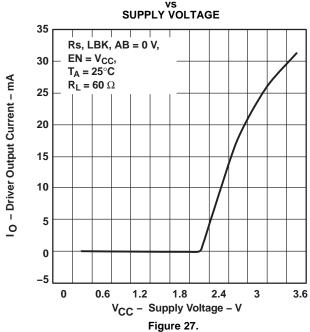


Figure 26.

## DRIVER OUTPUT CURRENT vs





#### **APPLICATION INFORMATION**

### **DIAGNOSTIC LOOPBACK (SN65HVD233)**

The loopback (LBK) function of the HVD233 is enabled with a high-level input to pin 5. This forces the driver into a recessive state and redirects the data (D) input at pin 1 to the received-data output (R) at pin 4. This allows the host controller to input and read back a bit sequence to perform diagnostic routines without disturbing the CAN bus. A typical CAN bus application is displayed in Figure 28.

If the LBK pin is not used it may be tied to ground (GND). However, it is pulled low internally (defaults to a low-level input) and may be left open if not in use.

### **AUTOBAUD LOOPBACK (SN65HVD235)**

The autobaud feature of the HVD235 is implemented by placing a logic high on pin 5 (AB). In autobaud, the *bus-transmit* function of the transceiver is disabled, while the *bus-receive* function and all of the normal operating functions of the device remain intact. With the autobaud function engaged, normal bus activity can be monitored by the device. However, if an error frame is generated by the local CAN controller, it is not transmitted to the bus. Only the host microprocessor can detect the error frame.

Autobaud detection is best suited to applications that have a known selection of baud rates. For example, a popular industrial application has optional settings of 125 kbps, 250 kbps, or 500 kbps. Once the logic high has been applied to pin 5 (AB) of the HVD235, assume a baud rate such as 125 kbps, then wait for a message to be transmitted by another node on the bus. If the wrong baud rate has been selected, an error message is generated by the host CAN controller. However, since the *bus-transmit* function of the device has been disabled, no other nodes receive the error message of the controller.

This procedure makes use of the CAN controller's status register indications of message received and error warning status to signal if the current baud rate is correct or not. The warning status indicates that the CAN chip error counters have been incremented. A message received status indicates that a good message has been received.

If an error is generated, reset the CAN controller with another baud rate, and wait to receive another message. When an error-free message has been received, the correct baud rate has been detected. A logic low may now be applied to pin 5 (AB) of the HVD235, returning the *bus-transmit* normal operating function to the transceiver.

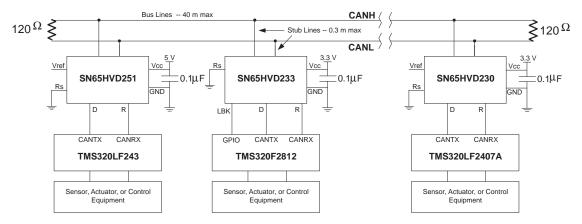


Figure 28. Typical HVD233 Application

#### ISO 11898 COMPLIANCE OF SN65HVD230 FAMILY OF 3.3-V CAN TRANSCEIVERS

#### Introduction

Many users value the low power consumption of operating their CAN transceivers from a 3.3 V supply. However, some are concerned about the interoperability with 5-V supplied transceivers on the same bus. This report analyzes this situation to address those concerns.



#### **Differential Signal**

CAN is a differential bus where complementary signals are sent over two wires and the voltage difference between the two wires defines the logical state of the bus. The differential CAN receiver monitors this voltage difference and outputs the bus state with a single-ended output signal.

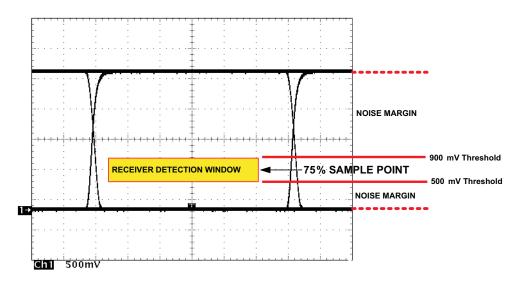


Figure 29. Typical SN65HVD230 Differential Output Voltage Waveform

The CAN driver creates the difference voltage between CANH and CANL in the dominant state. The dominant differential output of the SN65HVD230 is greater than 1.5 V and less than 3 V across a 60-ohm load. The minimum required by ISO 11898 is 1.5 V and maximum is 3 V. These are the same limiting values for 5 V supplied CAN transceivers. The bus termination resistors drive the recessive bus state and not the CAN driver.

A CAN receiver is required to output a recessive state with less than 500 mV and a dominant state with more than 900 mV difference voltage on its bus inputs. The CAN receiver must do this with common-mode input voltages from -2 V to 7 volts. The SN65HVD230 family receivers meet these same input specifications as 5-V supplied receivers.

### Common-Mode Signal

A common-mode signal is an average voltage of the two signal wires that the differential receiver rejects. The common-mode signal comes from the CAN driver, ground noise, and coupled bus noise. Obviously, the supply voltage of the CAN transceiver has nothing to do with noise. The SN65HVD230 family driver lowers the common-mode output in a dominant bit by a couple hundred millivolts from that of most 5-V drivers. While this does not fully comply with ISO 11898, this small variation in the driver common-mode output is rejected by differential receivers and does not effect data, signal noise margins or error rates.

#### Interoperability of 3.3-V CAN in 5-V CAN Systems

The 3.3-V supplied SN65HVD23x family of CAN transceivers are electrically interchangeable with 5-V CAN transceivers. The differential output is the same. The recessive common-mode output is the same. The dominant common-mode output voltage is a couple hundred millivolts lower than 5-V supplied drivers, while the receivers exhibit identical specifications as 5-V devices.

Electrical interoperability does not assure interchangeability however. Most implementers of CAN buses recognize that ISO 11898 does not sufficiently specify the electrical layer and that strict standard compliance alone does not ensure interchangeability. This comes only with thorough equipment testing.



#### **BUS CABLE**

The ISO-11898 Standard specifies a maximum bus length of 40 m and maximum stub length of 0.3 m with a maximum of 30 nodes. However, with careful design, users can have longer cables, longer stub lengths, and many more nodes to a bus. A large number of nodes requires a transceiver with high input impedance such as the HVD233.

The standard specifies the interconnect to be a single twisted-pair cable (shielded or unshielded) with  $120-\Omega$  characteristic impedance ( $Z_O$ ). Resistors equal to the characteristic impedance of the line terminate both ends of the cable to prevent signal reflections. Unterminated drop-lines (stubs) connecting nodes to the bus should be kept as short as possible to minimize signal reflections.

#### **SLOPE CONTROL**

The rise and fall slope of the SN65HVD233, SN65HVD234, and SN65HVD235 driver output can be adjusted by connecting a resistor from the Rs (pin 8) to ground (GND), or to a low-level input voltage as shown in Figure 30.

The slope of the driver output signal is proportional to the pin's output current. This slope control is implemented with an external resistor value of 10 k $\Omega$  to achieve a  $\approx$ 15 V/ $\mu$ s slew rate, and up to 100 k $\Omega$  to achieve a  $\approx$ 2.0 V/ $\mu$ s slew rate as displayed in Figure 31. Typical driver output waveforms with slope control are displayed in Figure 32.

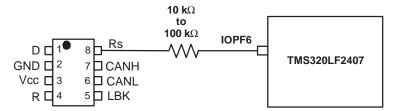


Figure 30. Slope Control/Standby Connection to a DSP

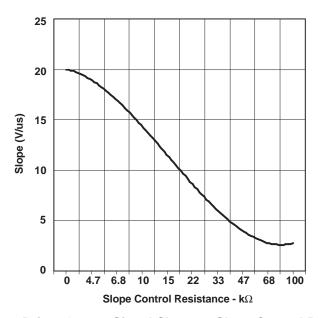


Figure 31. HVD233 Driver Output Signal Slope vs Slope Control Resistance Value



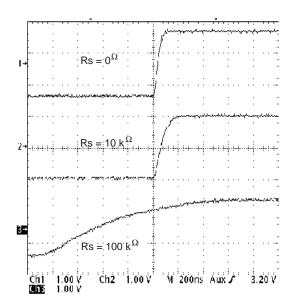


Figure 32. Typical SN65HVD233 250-kbps Output Pulse Waveforms With Slope Control

### **STANDBY**

If a high-level input ( $> 0.75 \ V_{CC}$ ) is applied to Rs (pin 8), the circuit enters a low-current, *listen only* standby mode during which the driver is switched off and the receiver remains active. The local controller can reverse this low-power standby mode when the rising edge of a dominant state (bus differential voltage  $>900 \ mV$  typical) occurs on the bus.



### **Revision History**

Cha	anges from Original (November 2002) to Revision A	Page
•	Changed the data sheet from Product Preview to Production for part number SN65HVD233.	1
Cha	anges from Revision A (March 2003) to Revision B	Page
•	Changed the data sheet from Product Preview to Production for part number SN65HVD234 and SN65HVD235	1
•	Added Table 2, Thermal Characteristics	15
•	Changed the APPLICATION INFORMATION section.	20
Cha	anges from Revision B (June 2003) to Revision C	Page
•	Added I <sub>O</sub> , Receiver output current to the Abs Max Table	3
Cha	anges from Revision C (March 2005) to Revision D	Page
•	Added Features Bullet: GIFT/ICT Compliant (SN65HVD234)	1
Cha	anges from Revision D (June 2005) to Revision E	Page
•	Added 60-Ω load test condition to Figure 19	17
•	Deleted INTEROPERABILITY WITH 5-V CAN SYSTEMS section	20
•	Added ISO 11898 COMPLIANCE OF SN65HVD230 FAMILY OF 3.3-V CAN TRANSCEIVERS section	20
Cha	anges from Revision E (October 2007) to Revision F	Page
_	Changed Figure 6. Receiver Test Circuit and Voltage Waveform, From: C. – 50 pF +20% to: C. – 15 pF +20%	9

#### PACKAGE OPTION ADDENDUM



ti.com 18-Sep-2008

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN65HVD233D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD233DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD233DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD233DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD234D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD234DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD234DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD234DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD235D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD235DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD235DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65HVD235DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.



## **PACKAGE OPTION ADDENDUM**

18-Sep-2008

In no event shall TI's liability arising out of s to Customer on an annual basis.	such information exceed th	e total purchase price of the	ne TI part(s) at issue in th	is document sold by T



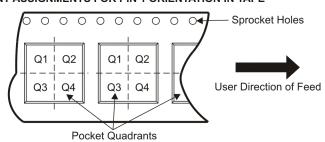
### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65HVD233DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN65HVD234DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN65HVD235DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1





\*All dimensions are nominal

7 til dillionorono di o mominar							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65HVD233DR	SOIC	D	8	2500	340.5	338.1	20.6
SN65HVD234DR	SOIC	D	8	2500	340.5	338.1	20.6
SN65HVD235DR	SOIC	D	8	2500	340.5	338.1	20.6

## D (R-PDSO-G8)

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.



#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

#### **Products Amplifiers** amplifier.ti.com Data Converters dataconverter.ti.com DSP dsp.ti.com Clocks and Timers www.ti.com/clocks Interface interface.ti.com Logic logic.ti.com Power Mgmt power.ti.com Microcontrollers microcontroller.ti.com www.ti-rfid.com RF/IF and ZigBee® Solutions www.ti.com/lprf

Applications	
Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated